

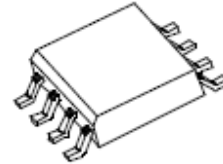


TVS ARRAY SERIES

FEATURES

- ✓ Protects 3.3, 5, 12, 15, 24 V Components
- ✓ Bidirectional
- ✓ Provides Electrically Isolated Protection
- ✓ 300 W @ 8/20 μs
- ✓ Protects 7 Lines
- ✓ SO-8 Packaging
- ✓ This is a Pb - Free Device
- ✓ All SMC parts are traceable to the wafer lot
- ✓ Additional testing can be offered upon request

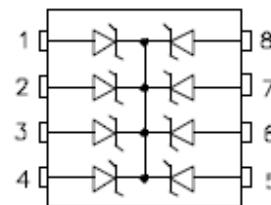
SO-8



DESCRIPTION

The SMDAXX-7 series of TVS array have been designed to provide bidirectional protection for sensitive electronics from damage due to voltage transients caused by electrostatic discharge (ESD), electrical fast transients (EFT), lightning and other voltage-induced transient events. The device can be used to protect combinations of seven bidirectional lines.

SCHEMATIC & PIN CONFIGURATION



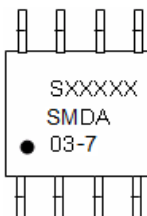
APPLICATION

- ✓ RS-232 & RS-422 Data Lines
- ✓ Microprocessor Based Equipment
- ✓ Notebooks, Desktops, & Servers
- ✓ LAN/WAN Equipment
- ✓ Serial and Parallel Port
- ✓ Peripherals

MECHANICAL CHARACTERISTICS

- ✓ SO-8 Surface Mount Package
- ✓ Approximate Weight: 0.1 grams
- ✓ PIN #1 Indicator: DOT on top of package
- ✓ Packaging: Tubes or Tape & Reel per EIA Standard 481

MARKING DIAGRAM



Where XXXXX is YYWWL

- SMDA03-7 = Part Name
- S = S
- YY = Year
- WW = Week
- L = Lot Number

Cautions: Molding resin
Epoxy resin UL:94V-0



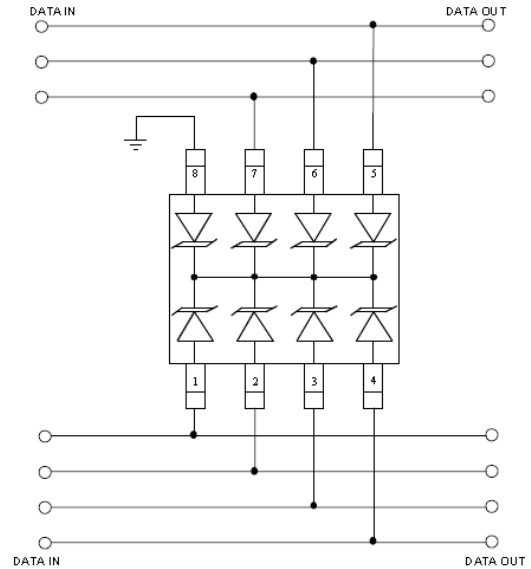
Technical Data
Data Sheet N0296, Rev. A

Circuit Diagram

The SMDAxxC-7 is designed to protect up to 7 data or I/O lines. They are bidirectional devices and may be used on lines where the signal polarities are above and below ground.

The devices are connected as follows:

- ✓ Pins 1, 2, 3, 4, 5, 6 and 7 are connected to the lines that are to be protected. Pin 8 is connected to ground. The ground connections should be made directly to the ground plane for best results. The path length is kept as short as possible to reduce the effects of parasitic inductance in the board traces.



Ordering Information:

Device	Package	Shipping
SMDA03-7 THRU SMDA24-7	SO-8 (Pb-Free)	2500pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification.

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
P	Peak Pulse Power, 8/20 μ s Waveshape	300	W
T _J	Operating Temperature	-55 to +125	$^{\circ}$ C
T _{STG}	Storage Temperature	-55 to +150	$^{\circ}$ C
T _L	Lead Soldering Temperature	260 (10 Sec.)	$^{\circ}$ C

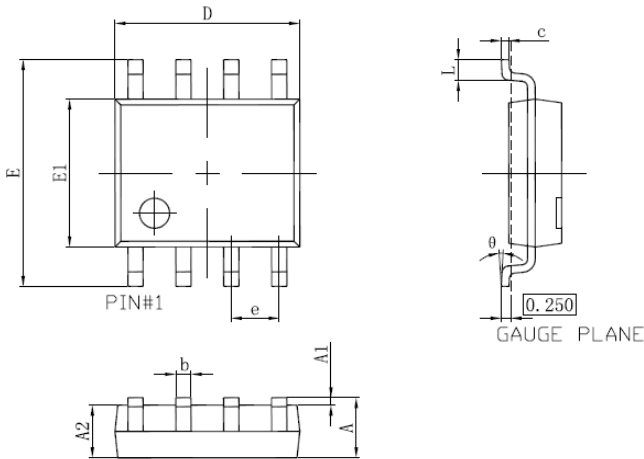


**Technical Data
Data Sheet N0296, Rev. A**

ELECTRICAL CHARACTERISTICS @ 25 °C

Part Number	Stand-off Voltage V_{vm} (v) Max	Breakdown Voltage V_{BR} @ 1mA (V) Min	Clamping Voltage V_c @ 1 A (V) Max	Leakage Current I_R @ V_{vm} (μ A) Max	Capacitance (f = 1MHz) C @ 0V (pF) Max	Temperature Coefficient of V_{BR} $a(V_{BR})$ mV/°C Max
SMDA03-7	3.3	4	7	200	300	-5
SMDA05-7	5.0	6	9.8	40	200	1
SMDA12-7	12.0	13.3	19	1	75	8
SMDA15-7	15.0	16.7	24	1	70	11
SMDA24-7	24.0	26.7	43	1	35	28

PACKAGE OUTLINES & DEMENSIONS (SO-8)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270 (BSC)		0.050 (BSC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.031
θ	0°	8°	0°	8°

TYPICAL CHARACTERISTICS

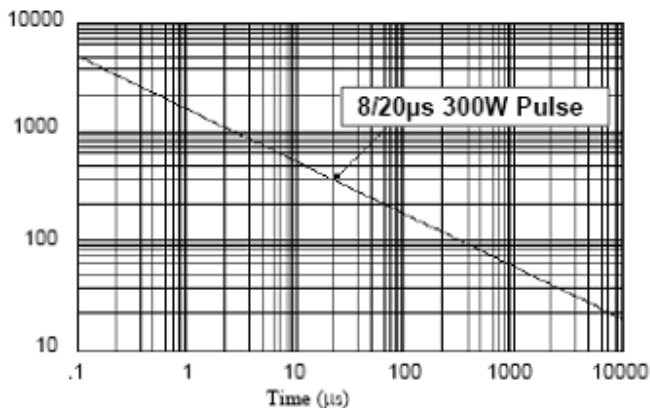


Figure 1. Peak Pulse Power Vs Pulse Time (μ s)

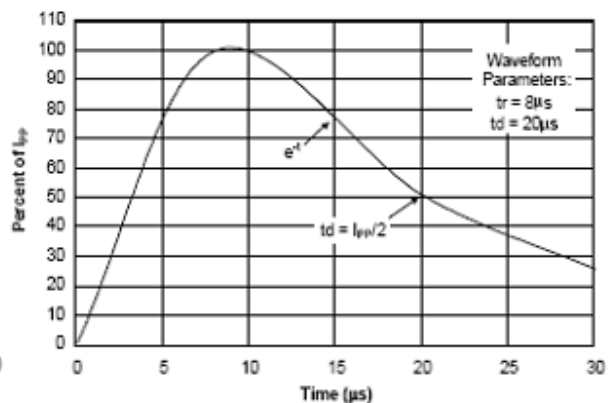


Figure 2. Pulse Wave Form

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